

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 9, line 15, and bridging to page 11, line 1, with the following rewritten paragraph:

- 1 semiconductor integrated circuit
- 2 circuit board
- 3 holder hole
- 4 conductive contact holder
- 5 conductive contact
- 7 connecting electrode
- 8 connecting electrode
- 9 first substrate
- 10 second substrate
- ~~11 holder substrate~~
- 12 spring member
- 13 first needle-like member
- 13a columnar member
- 13b contact member
- 13c sharp-pointed portion
- 13d flange member
- 13e retaining protruding member
- 13f boss member
- 13g through hole

- 14 second needle-like member
- 14a support member
- 14b boss member
- 14c retaining protruding member
- 14d flange member
- 14e contact member
- 16 rod-like body
- 17 gripping member
- 18 grinding member
- 19 hole portion
- 20 drill
- 21 grinding member
- 22 first needle-like member
- 22a through hole
- 22b first hole portion
- 22c second hole portion
- 24 rod-like body
- 25 gripping member
- 26 small bore drill
- 27 hole portion
- 28 large bore drill
- 29 hole portion
- 30 needle-like member
- 30a contact member
- 101 plunger
- 102 barrel
- 103 spring

- 105 contact member
- 106 columnar member
- 107 support member
- 108 contact member
- 109 columnar member
- ~~109 hollow portion~~
- 110 hollow portion

Please replace the paragraph beginning at page 11, line 23, with the following rewritten paragraph:

The circuit board 2 functions as an example of a circuit or a circuit board in the scope of the claims, and includes an inspection circuit for inspecting electrical characteristics of the semiconductor integrated circuit 1 which is an inspection object. Specifically, the circuit formed on the circuit board 2 has a function to generate and transmit electrical signals for inspection. Furthermore, on a surface of the ~~circuit board 2~~ semiconductor integrated circuit 1 to contact the conductive contact holder 4, a connecting electrode 8 is arranged for electrically connecting the built-in inspection circuit to the conductive contact 5.

Please replace the paragraph beginning at page 12, line 6, with the following rewritten paragraph:

The holder holes 3 have a columnar shape, and is formed to penetrate ~~a holder substrate 11~~ the conductive contact holder 4 correspondingly to an arrangement pattern of a plurality of the

connecting electrodes 8 on the semiconductor integrated circuit 1 to be inspected. The holder holes 3 functions as a positioning unit and a guide unit for accommodating the conductive contact 5. The holder hole 3 is formed by applying etching, punching, or a laser beam, electron beam, ion beam, wire electric discharge, drilling, or the like to the respective first substrate 9 and the second substrate 10.

Please replace the paragraph beginning at page 22, line 24, and bridging to page 23, line 8, with the following rewritten paragraph:

The reason why such advantages can be achieved in the embodiment is that a hole in the first needle-like member 13 for accommodating the support member 14a of the second needle-like member 14 is of a through hole shape having a constant inner diameter. That is, when the hole portion formed in the needle-like member ~~[[14]]~~ 13 is formed in a cavity-like shape having the bottom as shown in Fig. 8, the hole portion is required to have an opening end at least on the second needle-like member 14 side, and therefore, the direction of the rod-like body 16 needs to be changed to form the hole portion. On the other hand, in the embodiment, the first needle-like member 13 has the structure in which the through hole 13g has the opening ends on both ends of the longitudinal direction, and therefore, drilling process in manufacturing with the drill 20 can be performed from the side opposite to the second needle-like member 14. With this structure, the aforementioned advantages can be achieved in the embodiment.